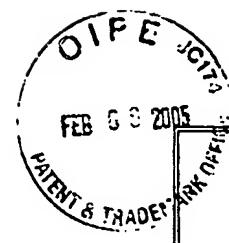


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		APPLICANT Yuri KOKOTOV et al.				
		FILING DATE November 14, 2003	GROUP			
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<i>J</i>	Moyné, James et al. "A Run-to-Run Control Framework for VLSI Manufacturing." <i>Microelectronic Processing '93 Conference Proceedings</i> . September 1993.					
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SHEET 1 OF 1

**INFORMATION DISCLOSURE
CITATION IN AN
APPLICATION**

(PTO-1449)

ATTY. DOCKET NO.
006365 USA/
MTCG/PCTRI.

SERIAL NO.
10/712,273

APPLICANT

FILING DATE
November 14, 2003

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						Yes	No
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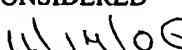
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EXAMINER	<i>J</i>			DATE CONSIDERED	<i>11/10/04</i>	

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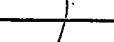
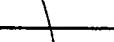
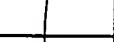
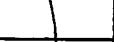
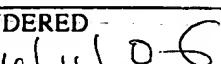
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			APPLICANT Yuri KOKOTOV et al.			
			FILING DATE November 14, 2003	GROUP		
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						Yes	No
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	4,757,259	07/12/88	Charpentier			11/05/86
	4,796,194	01/03/89	Atherton			08/20/86
	4,901,218	02/13/90	Cornwell			03/04/88
	4,938,600	07/03/90	Into			02/09/89
	4,967,381	10/30/90	Lane et al.			07/06/89
	5,089,970	02/18/92	Lee et al.			10/05/89
	5,108,570	04/28/92	Wang			03/30/90
	5,208,765	05/04/93	Turnbull			07/20/90
	5,220,517	06/15/93	Sierk et al.			08/31/90
	5,226,118	07/06/93	Baker et al.			01/29/91
	5,231,585	07/27/93	Kobayashi et al.			06/20/90
	5,236,868	08/17/93	Nulman			04/20/90
	5,260,868	11/09/93	Gupta et al.			10/15/91

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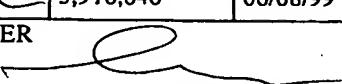
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INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)			ATTY. DOCKET NO. 006365 USA/MTCG/PCTRL	SERIAL NO. 10/712,273		
			APPLICANT Yuri KOKOTOV et al.			
			FILING DATE November 14, 2003	GROUP		
U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,270,222	12/14/93	Moslehi			12/31/90
	5,283,141	02/01/94	Yoon et al.			03/05/92
	5,295,242	03/15/94	Mashruwala et al.			11/02/90
	5,309,221	05/03/94	Fischer et al.			12/31/91
	5,329,463	07/12/94	Sierk et al.			01/13/93
	5,338,630	08/16/94	Yoon et al.			11/18/93
	5,347,446	09/13/94	Iino et al.			02/10/92
	5,367,624	11/22/94	Cooper			06/11/93
	5,375,064	12/20/94	Bollinger			12/02/93
	5,398,336	03/14/95	Tantry et al.			06/16/93
	5,408,405	04/18/95	Mozumder et al.			09/20/93
	5,410,473	04/25/95	Kaneko et al.			12/16/92
	5,420,796	05/30/95	Weling et al.			12/23/93
	5,427,878	06/27/95	Corliss			05/16/94
	5,469,361	11/21/95	Moyne			06/06/94
	5,485,082	01/16/96	Wisspeintner et al.			04/05/90
	5,490,097	02/06/96	Swenson et al.			08/06/93
	5,495,417	02/27/96	Fuduka et al.			03/16/93
	5,497,316	03/05/96	Sierk et al.			04/04/95
	5,497,381	03/05/96	O'Donoghue et al.			06/01/95
	5,503,707	04/02/96	Maung et al.			09/22/93
	5,508,947	04/16/96	Sierk et al.			05/13/94
	5,511,005	04/23/96	Abbe et al.			02/16/94
	5,525,808	06/11/96	Irie et al.			12/20/94
	5,526,293	06/11/96	Mozumder et al.			12/17/93
	5,534,289	07/09/96	Bilder et al.			01/03/95
	5,541,510	07/30/96	Danielson			04/06/95
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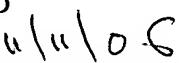
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			APPLICANT Yuri KOKOTOV et al.			
			FILING DATE November 14, 2003		GROUP	
U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
<i>Ch</i>	5,586,039	12/17/96	Hirsch et al.			02/27/95
	5,599,423	02/04/97	Parker et al.			06/30/95
	5,602,492	02/11/97	Cresswell et al.			04/28/94
	5,603,707	02/18/97	Trombetta et al.			11/28/95
	5,617,023	04/01/97	Skalski			02/02/95
	5,627,083	05/06/97	Tounai			05/12/95
	5,629,216	05/13/97	Wijaranakula et al.			02/27/96
	5,642,296	06/24/97	Saxena			07/29/93
	5,646,870	07/08/97	Krivokapic et al.			02/13/95
	5,649,169	07/15/97	Berezin et al.			06/20/95
	5,655,951	08/12/97	Meikle et al.			09/29/95
	5,657,254	08/12/97	Sierk et al.			04/15/96
	5,661,669	08/26/97	Mozumder et al.			06/07/95
	5,663,797	09/02/97	Sandhu			05/16/96
	5,664,987	09/09/97	Renteln			09/04/96
	5,665,199	09/09/97	Sahota et al.			06/23/95
	5,667,424	09/16/97	Pan			09/25/96
	5,674,787	10/07/97	Zhao et al.			01/16/96
	5,694,325	12/02/97	Fukuda et al.			11/22/95
	5,698,989	12/16/97	Nulman			09/13/96
	5,719,495	02/17/98	Moslehi			06/05/96
	5,719,796	02/17/98	Chen			12/04/95
	5,735,055	04/07/98	Hochbein et al.			04/23/96
<i>Ch</i>	5,740,429	04/14/98	Wang et al.			07/07/95
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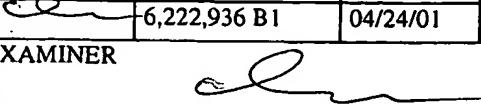
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
<i>CL</i>	5,751,582	05/12/98	Saxena et al.			09/24/96
<i>CL</i>	5,754,297	05/19/98	Nulman			04/14/97
<i>CL</i>	5,761,064	06/02/98	La et al.			10/06/95
<i>CL</i>	5,761,065	06/02/98	Kittler et al.			03/30/95
<i>CL</i>	5,764,543	06/09/98	Kennedy			06/16/95
<i>CL</i>	5,777,901	07/07/98	Berezin et al.			09/29/95
<i>CL</i>	5,787,021	07/28/98	Samaha			12/18/95
<i>CL</i>	5,787,269	07/28/98	Hyodo			09/19/95
<i>CL</i>	5,808,303	09/15/98	Schlagheck et al.			01/29/97
<i>CL</i>	5,812,407	09/22/98	Sato et al.			08/12/97
<i>CL</i>	5,823,854	10/20/98	Chen			05/28/96
<i>CL</i>	5,828,778	10/27/98	Hagi et al.			07/12/96
<i>CL</i>	5,832,224	11/03/98	Fehskens et al.			06/14/96
<i>CL</i>	5,844,554	12/01/98	Geller et al.			09/17/96
<i>CL</i>	5,857,258	01/12/99	Penzes et al.			05/12/94
<i>CL</i>	5,859,964	01/12/99	Wang et al.			10/25/96
<i>CL</i>	5,859,975	01/12/99	Brewer et al.			08/09/96
<i>CL</i>	5,862,054	01/19/99	Li			02/20/97
<i>CL</i>	5,863,807	01/26/99	Jang et al.			03/15/96
<i>CL</i>	5,867,389	02/02/99	Hamada et al.			11/26/96
<i>CL</i>	5,870,306	02/09/99	Harada			06/13/97
<i>CL</i>	5,883,437	03/16/99	Maruyama et al.			12/28/95
<i>CL</i>	5,889,991	03/30/99	Consolatti et al.			12/06/96
<i>CL</i>	5,901,313	05/04/99	Wolfe et al.			09/02/97
<i>CL</i>	5,903,455	05/11/99	Sharpe, Jr. et al.			12/12/96
<i>CL</i>	5,910,011	06/08/99	Cruse			05/12/97
<i>CL</i>	5,910,846	06/08/99	Sandhu			08/19/97
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,912,678	06/15/99	Saxena et al.			04/14/97
	5,916,016	06/29/99	Bothra			10/23/97
	5,923,553	07/13/99	Yi			10/05/96
	5,926,690	07/20/99	Toprac et al.			05/28/97
	5,930,138	07/27/99	Lin et al.			09/10/97
	5,940,300	08/17/99	Ozaki			05/08/97
	5,943,237	08/24/99	Van Boxem			10/17/97
	5,960,185	09/28/99	Nguyen			06/24/96
	5,960,214	09/28/99	Sharpe, Jr. et al.			12/04/96
	5,961,369	10/05/99	Bartels et al.			06/04/98
	5,963,881	10/05/99	Kahn et al.			10/20/97
	5,978,751	11/02/99	Pence et al.			02/25/97
	5,982,920	11/09/99	Tobin, Jr. et al.			01/08/97
	6,002,989	12/14/99	Shiba et al.			04/01/97
	6,017,771	01/25/00	Yang et al.			04/27/98
	6,041,263	03/21/00	Boston et al.			10/01/97
	6,041,270	03/21/00	Steffan et al.			12/05/97
	6,054,379	04/25/00	Yau et al.			02/11/98
	6,064,759	05/16/00	Buckley et al.			11/06/97
	6,072,313	06/06/00	Li et al.			06/17/97
	6,074,443	06/13/00	Venkatesh et al.			01/29/98
	6,077,412	06/20/00	Ting et al.			10/30/98
	6,078,845	06/20/00	Friedman			11/25/96
	6,094,688	07/25/00	Mellen-Garnett et al.			03/12/98
	6,097,887	08/01/00	Hardikar et al.			10/27/97
	6,108,092	08/22/00	Sandhu			06/08/99
	6,111,634	08/29/00	Pecen et al.			05/28/97
	6,112,130	08/29/00	Fukuda et al.			10/01/97
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	6,127,263	10/03/00	Parikh			07/10/98
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	6,136,163	10/24/00	Cheung et al.			03/05/99
	6,141,660	10/31/00	Bach et al.			07/16/98
	6,143,646	11/07/00	Wetzel			06/03/97
	6,148,239	11/14/00	Funk et al.			12/12/97
	6,148,246	11/14/00	Kawazome			06/10/98
	6,150,664	11/21/00	Su			06/29/99
	6,159,075	12/12/00	Zhang			10/13/99
	6,159,644	12/12/00	Satoh et al.			03/06/96
	6,161,054 B1	12/12/00	Rosenthal et al.			09/17/98
	6,169,931 B1	01/02/01	Runnels			07/29/98
	6,172,756 B1	01/09/01	Chalmers et al.			12/11/98
	6,175,777 B1	01/16/01	Kim			01/16/98
	6,178,390 B1	01/23/01	Jun			09/08/98
	6,183,345 B1	02/06/01	Kamono et al.			03/20/98
	6,185,324 B1	02/06/01	Ishihara et al.			01/31/95
	6,191,864 B1	02/20/01	Sandhu			02/29/00
	6,192,291 B1	02/20/01	Kwon			10/08/98
	6,197,604 B1	03/06/01	Miller et al.			10/01/98
	6,204,165 B1	03/20/01	Ghoshal			06/24/99
	6,210,983 B1	04/03/01	Atchison et al.			06/15/99
	6,211,094 B1	04/03/01	Jun et al.			08/23/99
	6,214,734 B1	04/10/01	Bothra et al.			11/20/98
	6,217,412 B1	04/17/01	Campbell et al.			08/11/99
	6,219,711 B1	04/17/01	Chari			10/01/97
	6,222,936 B1	04/24/01	Phan et al.			09/13/99
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	6,226,792 B1	05/01/01	Goiffon et al.			10/14/98
	6,230,069 B1	05/08/01	Campbell et al.			06/26/98
	6,236,903 B1	05/22/01	Kim et al.			09/25/98
	2001/0001755 A1	05/24/01	Sandhu et al.			12/29/00
	6,240,330 B1	05/29/01	Kurtzberg et al.			05/28/97
	6,240,331 B1	05/29/01	Yun			08/18/98
	2001/0003084 A1	06/07/01	Finarov			12/04/00
	6,245,581 B1	06/12/01	Bonser et al.			04/19/00
	6,248,602 B1	06/19/01	Bode et al.			11/01/99
	6,249,712 B1	06/19/01	Boiquaye			09/25/96
	6,252,412 B1	06/26/01	Talbot et al.			01/08/99
	6,253,366 B1	06/26/01	Mutschler, III			03/31/99
	6,263,255 B1	07/17/01	Tan et al.			05/18/98
	6,271,670 B1	08/07/01	Caffey			02/08/99
	6,276,989 B1	08/21/01	Campbell et al.			08/11/99
	6,278,899 B1	08/21/01	Piche et al.			10/06/98
	6,280,289 B1	08/28/01	Wiswesser et al.			11/02/98
	6,284,622 B1	09/04/01	Campbell et al.			10/25/99
	6,287,879 B1	09/11/01	Gonzales et al.			08/11/99
	6,290,572 B1	09/18/01	Hofmann			03/23/00
	6,292,708 B1	09/18/01	Allen et al.			06/11/98
	6,298,274 B1	10/02/01	Inoue			09/01/99
	6,298,470 B1	10/02/01	Breiner et al.			04/15/99
	6,303,395 B1	10/16/01	Nulman			06/01/99
	6,304,999 B1	10/16/01	Toprac et al.			10/23/00
	2001/0030366 A1	10/18/01	Nakano et al.			03/07/01
	6,307,628 B1	10/23/01	Lu et al.			08/18/00
	6,314,379 B1	11/06/01	Hu et al.			12/04/97
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U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
<i>clu</i>	2001/0039462 A1	11/08/01	Mendez et al.			04/02/01
	2001/0040997 A1	11/15/01	Tsap et al.			05/15/01
	2001/0042690 A1	11/22/01	Talieh			12/14/00
	2001/0044667 A1	11/22/01	Nakano et al.			05/16/01
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	6,334,807 B1	01/01/02	Lebel et al.			04/30/99
	6,336,841 B1	01/08/02	Chang			03/29/01
	6,340,602 B1	01/22/02	Johnson et al.			02/12/01
	6,345,288 B1	02/05/02	Reed et al.			05/15/00
	6,345,315 B1	02/05/02	Mishra			08/12/98
	6,346,426 B1	02/12/02	Toprac et al.			11/17/00
	2002/0032499	03/14/02	Wilson et al.			05/04/01
	6,360,133 B1	03/19/02	Campbell et al.			06/17/99
	6,360,184 B1	03/19/02	Jacquez			03/26/97
	6,363,294 B1	03/26/02	Coronel et al.			12/29/98
	6,366,934 B1	04/02/02	Cheng et al.			06/02/99
	6,368,879 B1	04/09/02	Toprac			09/22/99
	6,368,883 B1	04/09/02	Bode et al.			08/10/99
	6,368,884 B1	04/09/02	Goodwin et al.			04/13/00
	6,379,980 B1	04/30/02	Toprac			07/26/00
	6,388,253 B1	05/14/02	Su			11/02/00
	6,389,491 B1	05/14/02	Jacobson et al.			03/23/99
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	6,397,114 B1	05/28/02	Eryurek et al.			05/03/99
	6,400,162 B1	06/04/02	Mallory et al.			07/21/00
	6,405,096 B1	06/11/02	Toprac et al.			08/10/99
	6,405,144 B1	06/11/02	Toprac et al.			01/18/00
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U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	2002/0070126 A1	06/13/02	Sato et al.			09/19/01
	2002/0077031 A1	06/20/02	Johannson et al.			07/06/01
	2002/0081951 A1	06/27/02	Boyd et al.			02/20/02
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	6,435,952 B1	08/20/02	Boyd et al.			06/30/00
	6,438,438 B1	08/20/02	Takagi et al.			01/02/98
	2002/0113039 A1	08/22/02	Mok et al.			02/16/01
	6,440,295 B1	08/27/02	Wang			02/04/00
	6,442,496 B1	08/27/02	Pasadyn et al.			08/08/00
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	2002/0149359 A1	10/17/02	Crouzen et al.			08/18/01
	6,470,230 B1	10/22/02	Toprac et al.			01/04/00
	6,479,902 B1	11/12/02	Lopatin et al.			06/29/00
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	6,482,660 B2	11/19/02	Conchieri et al.			03/19/01
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		APPLICANT Yuri KOKOTOV et al.				
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	09/363,966	07/29/99	Arackaparambil et al.	Computer Integrated Manufacturing Techniques		
	09/469,227	12/22/99	Sonekh et al.	Multi-Tool Control System, Method and Medium		
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System		
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder		
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers		
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service		
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	10/172,977	06/18/02	Shanmugasundram et al.	Method, System and Medium for Process Control for the Matching of Tools, Chambers and/or Other Semiconductor-Related Entities			
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	10/174,370	06/18/02	Shanmugasundram et al.	Feedback Control of Plasma-Enhanced Chemical Vapor Deposition Processes			
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	05-151231	06/18/93	Japan			X	
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	436383B	05/28/01	Taiwan			X	
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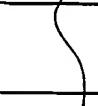
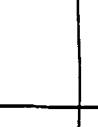
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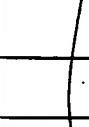
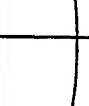
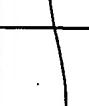
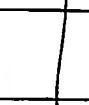
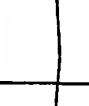
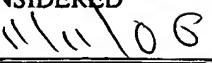
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INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)		ATTY. DOCKET NO. 006365 USA/MTCG/PCTRL	SERIAL NO. 10/712,273
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